

SSC8L422GN6

N-Channel Enhancement Mode MOSFET

Features

V _{DS}	V _{GS}	R _{DS(ON)} Typ.	ID
40V	+20V	3mΩ@10V	110A
	<u> - 20</u> v	5.5mΩ@4V5	HUA

> Description

This device is N-Channel enhancement mode MOSFET. Uses SGT Technology and design to provide excellent RDSON with low gate charge. This device is suitable for use in DC-DC conversion, power switch and charging circuit.

100% UIS + ΔVDS + Rg Tested!

> Applications

- DC/DC converters
- Power supplies
- Motor Drive Control
- Synchronous rectification

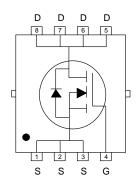
Ordering Information

Device	Package	Shipping	
SSC8L422GN6	PDFN5X6-8L	5000/Reel	

Pin configuration



PDFN5X6-8L



Pin Configuration (Top View)



<u>Marking</u>

(XXYY: Internal Traceability Code)



➤ Absolute Maximum Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit		
V_{DSS}	Drain-to-Source Volta	Drain-to-Source Voltage		V	
V_{GSS}	Gate-to-Source Volta	Gate-to-Source Voltage		V	
	Continuous Prais Current d	T _C =25℃	110	^	
l _D	Continuous Drain Current d	T _C =100°C	60	Α	
	Continuous Drain Current ^a	T _A =25°C	28	^	
IDSM		T _A =70°C	20	A	
I _{DM}	Pulsed Drain Curren	Pulsed Drain Current ^b		А	
Б	D D:	Tc=25°C	62.5	107	
P _D	Power Dissipation ^c	T _C =100°C	25	W	
	Power Dissipation ^a	T _A =25°C	4.2	107	
P _{DSM}		T _A =70°C	2.7	W	
I _{AS}	Avalanche Current b L=0.5mH Single Pulse		25	А	
Eas	Avalanche Energy ^b L=0.5mH Single Pulse		156	mJ	
TJ	Operation junction temperature		-55~150	°C	
T _{STG}	Storage temperature range		-55~150	$^{\circ}$	

➤ Thermal Resistance Ratings (T_A=25°C unless otherwise noted)

Symbol	Parameter	Ratings	Unit
$R_{\theta JA}$	Junction-to-Ambient Thermal Resistance a	30	°C/W
R ₀ JC	Junction-to-Case Thermal Resistance	2	C/ VV

Note:

- a. The value of R_{θJA} is measured with the device mounted on 1 in² FR-4 board with 2oz.copper, in a still air environment with T_A=25 °C. The value in any given application depends on the user is specific board design. The power dissipation is based on the t≤10s thermal resistance rating.
- b. Repetitive rating, pulse width limited by junction temperature.
- c. The power dissipation P_D is based on $T_{J(MAX)}$ =150°C, using junction-to-case thermal resistance, and is more useful in setting the upper dissipation limit for cases where additional heat sinking is used.
- d. The maximum current rating is package limited.

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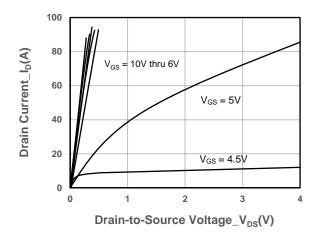


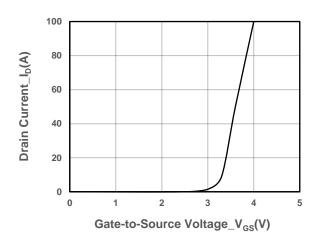
\succ Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250µA	40			V	
Gate Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_D = 250uA$	1.5	2.5	3.5	V	
Drain-Source On-Resistance	D	$V_{GS} = 10V, I_D = 20A$		3	3.9	m0	
Dialii-Source Off-Resistance	R _{DS(on)}	$V_{GS} = 4.5V, I_{D} = 10A$		5.5	7	mΩ	
Zero Gate Voltage Drain Current	loss	V _{DS} = 40V, V _{GS} = 0V			1	μA	
Gate-Source Leak Current	lgss	$V_{GS} = \pm 20V, V_{DS} = 0V$			±100	nA	
Forward Voltage	V_{SD}	V _{GS} = 0V, I _S = 5A			1.3	V	
Gate Resistance	R _G	$V_{DS} = 0V, f = 1MHz$		2.6		Ω	
Input Capacitance	C _{ISS}	V 20V V 0V		1900			
Output Capacitance	Coss	$V_{DS} = 20V$, $V_{GS} = 0V$, $f = 1MHz$		800		pF	
Reverse Transfer Capacitance	C _{RSS}	I = IIVIDZ		45			
Total Gate Charge	Q _G	V 40V V 20V		29			
Gate to Source Charge	Q _{GS}	$V_{GS} = 10V, V_{DS} = 32V,$ $I_{D} = 20A$		6.8		nC	
Gate to Drain Charge	Q _{GD}	1 _D = 20A		5.5			
Turn-on Delay Time	T _{D(ON)}			4.5			
Rise Time	Tr	$V_{GS} = 10V, V_{DS} = 20V,$		6.8			
Turn-off Delay Time	T _{D(OFF)}	$I_D=20A,R_G=3\Omega$		23		ns	
Fall Time	Tf			3.7			
Diode Recovery Time	Trr	I _F =50A, di/dt=100A/us		16		ns	
Diode Recovery Charge	Qrr	I _F =50A, di/dt=100A/us		36		nC	



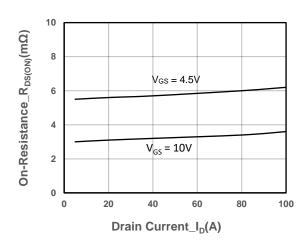
➤ Typical Performance Characteristics (T_A=25°C unless otherwise noted)

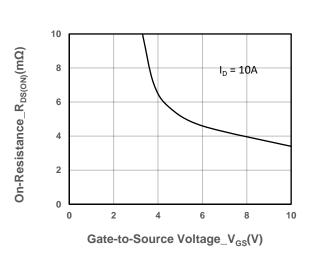




Output Characteristics

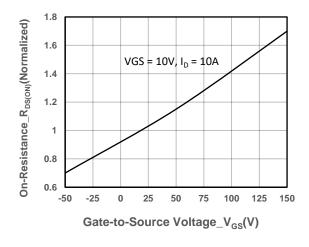
Transfer Characteristics

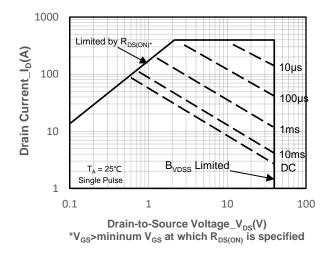




On-Resistance vs. Drain Current and Gate Voltag

On-Resistance vs. Gate-to-Source Voltage



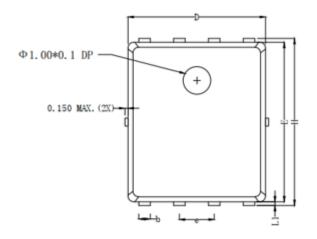


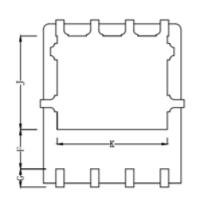
On-Resistance vs. Junction Temperature

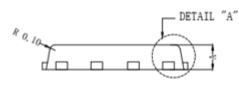
Safe Operating Area vs. Junction-to-Ambient

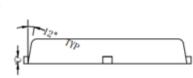


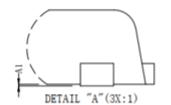
Package Information











Comple al	Dimensions In Millimeters			
Symbol	Min.	Nom.	Max.	
Α	0.90	1.00	1.10	
A1	0.00	0.03	0.05	
b	0.25	0.03	0.35	
С	0.254 REF			
D	4.80	4.90	5.00	
F	1.35 REF			
E	5.65	5.75	5.85	
е	1.27 BSC			
Н	5.90	6.00	6.10	
L1	0.10	0.13	0.16	
G	0.55 REF			
K	4.00 REF			
J	3.45 REF			



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